



General Description

- Latest advanced trench technology
- Low $R_{DS(ON)}$
- High Current Capability
- RoHS and Halogen-Free Compliant

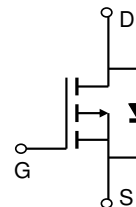
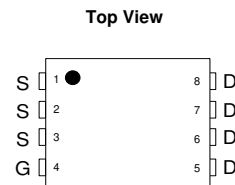
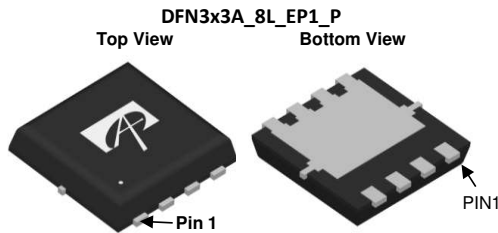
Applications

- Load switch application
- Battery protection application

Product Summary

V_{DS}	-20V
I_D (at $V_{GS}=-4.5V$)	-34A
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	< 4.8m Ω
$R_{DS(ON)}$ (at $V_{GS}=-2.5V$)	< 7.2m Ω

100% UIS Tested
100% Rg Tested



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AONR21117	DFN 3x3 EP	Tape & Reel	5000

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current ^A	I_D	$T_C=25^\circ C$	-34
		$T_C=100^\circ C$	-34
Pulsed Drain Current ^C	I_{DM}	-136	A
Continuous Drain Current	I_{DSM}	$T_A=25^\circ C$	-26.5
		$T_A=70^\circ C$	-21
Avalanche Current ^C	I_{AS}	50	A
Avalanche energy	E_{AS}	125	mJ
Power Dissipation ^B	P_D	$T_C=25^\circ C$	43
		$T_C=100^\circ C$	17
Power Dissipation ^A	P_{DSM}	$T_A=25^\circ C$	5.0
		$T_A=70^\circ C$	3.2
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	20	25	$^\circ C/W$
Maximum Junction-to-Ambient ^{A,D}		45	55	$^\circ C/W$
Maximum Junction-to-Case	$R_{\theta JC}$	2.4	2.9	$^\circ C/W$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units	
STATIC PARAMETERS							
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =-250μA, V _{GS} =0V	-20			V	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-20V, V _{GS} =0V T _J =55°C			-1 -5	μA	
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±8V			±100	nA	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.3	-0.7	-1.1	V	
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-20A T _J =125°C		4	4.8	mΩ	
		V _{GS} =-2.5V, I _D =-20A		5.4	6.5		
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-20A		100		S	
V _{SD}	Diode Forward Voltage	I _S =-1A, V _{GS} =0V		-0.6	-1	V	
I _S	Maximum Body-Diode Continuous Current ^G				-34	A	
DYNAMIC PARAMETERS							
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-10V, f=1MHz		6560		pF	
C _{oss}	Output Capacitance				770		pF
C _{rss}	Reverse Transfer Capacitance				700		pF
R _g	Gate resistance	f=1MHz		3	6	Ω	
SWITCHING PARAMETERS							
Q _{g(4.5V)}	Total Gate Charge	V _{GS} =-4.5V, V _{DS} =-10V, I _D =-20A		63	88	nC	
Q _{gs}	Gate Source Charge				8		nC
Q _{gd}	Gate Drain Charge				19		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =-4.5V, V _{DS} =-10V, R _L =0.5Ω, R _{GEN} =3Ω		24		ns	
t _r	Turn-On Rise Time				40		ns
t _{D(off)}	Turn-Off DelayTime				200		ns
t _f	Turn-Off Fall Time				75		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =-20A, di/dt=500A/μs		38		ns	
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =-20A, di/dt=500A/μs		105		nC	

A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The Power dissipation P_{DSM} is based on R_{θJA} t ≤ 10s and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature T_{J(MAX)}=150° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

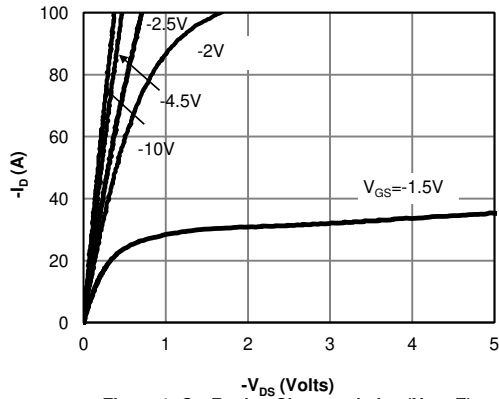


Figure 1: On-Region Characteristics (Note E)

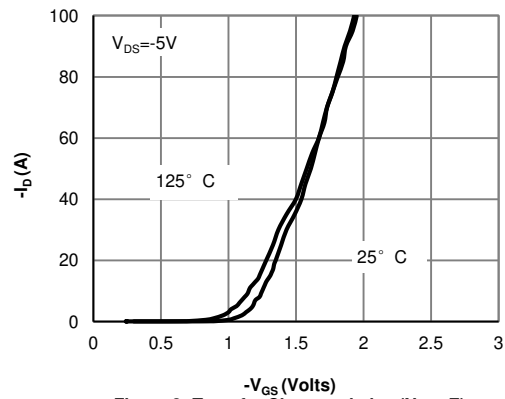


Figure 2: Transfer Characteristics (Note E)

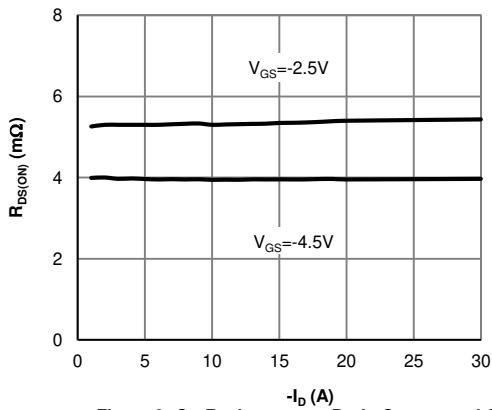


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

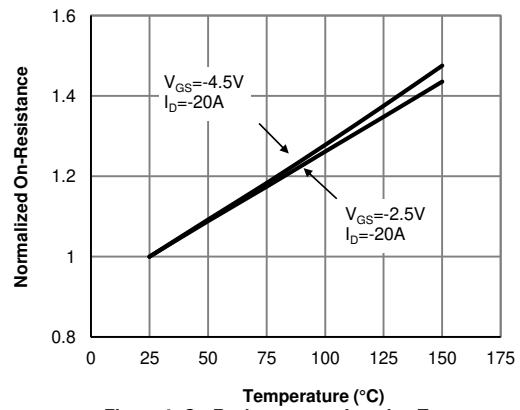


Figure 4: On-Resistance vs. Junction Temperature (Note E)

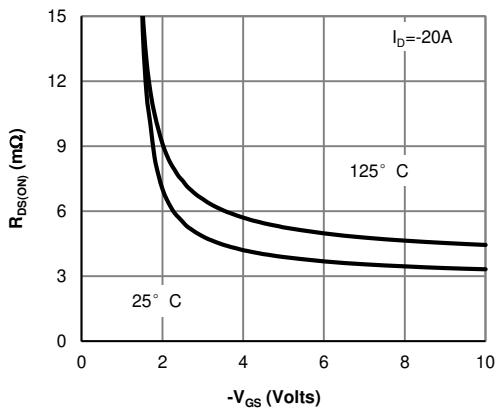


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

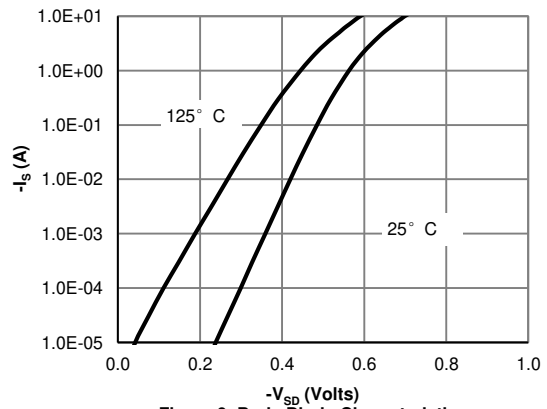


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

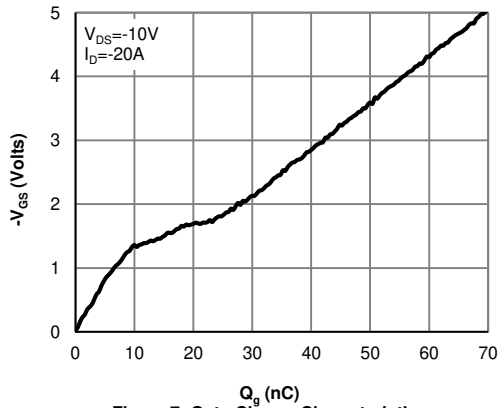


Figure 7: Gate-Charge Characteristics

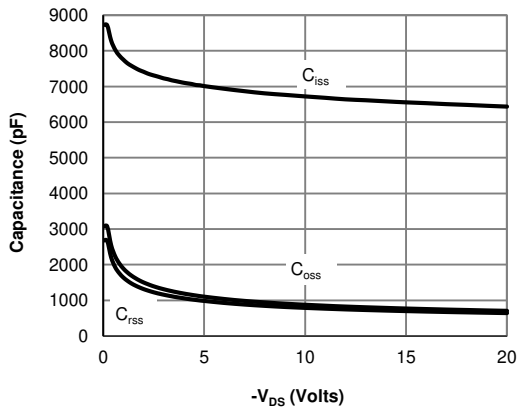


Figure 8: Capacitance Characteristics

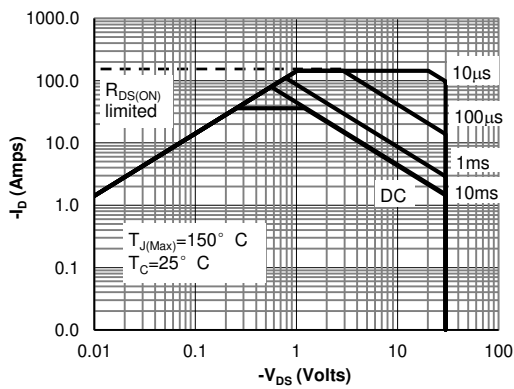


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

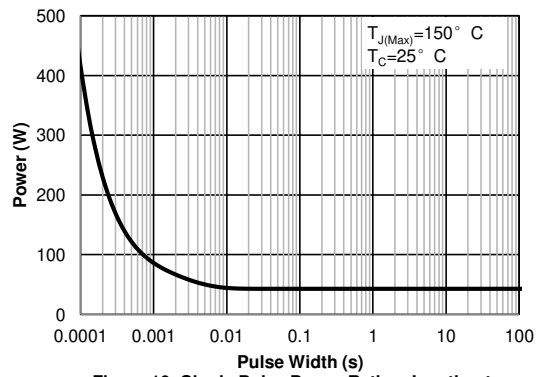


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

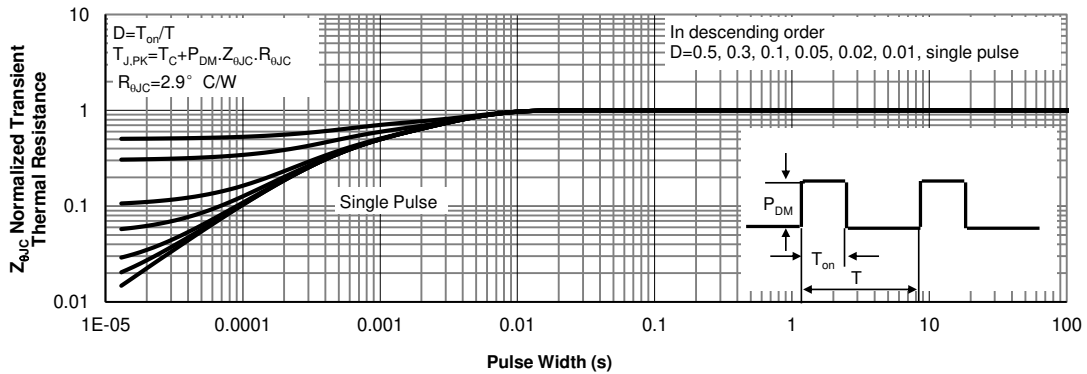


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

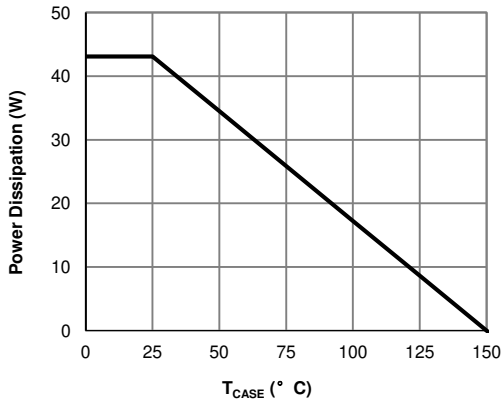


Figure 12: Power De-rating (Note F)

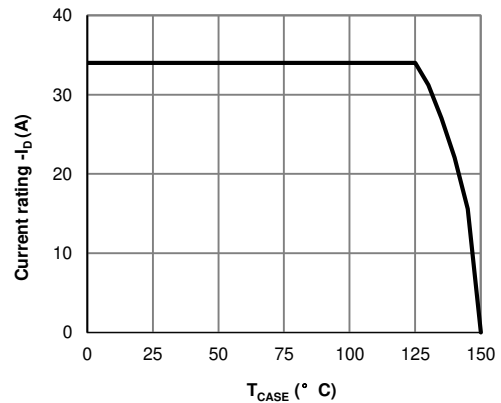


Figure 13: Current De-rating (Note F)

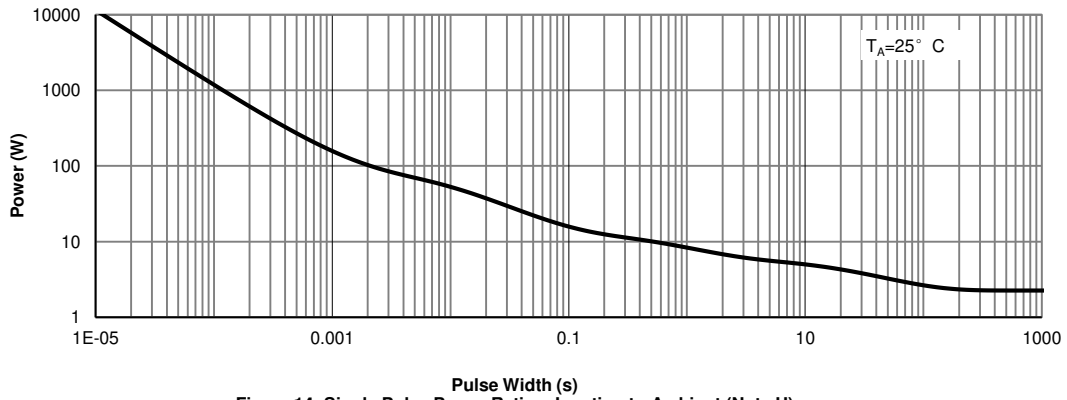


Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

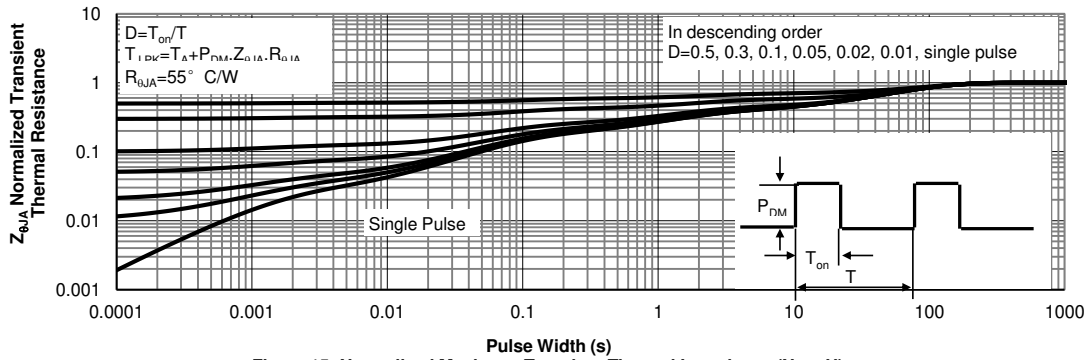
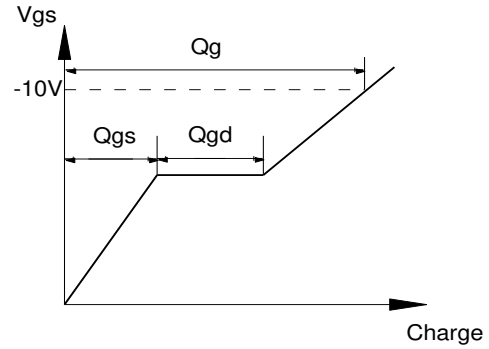
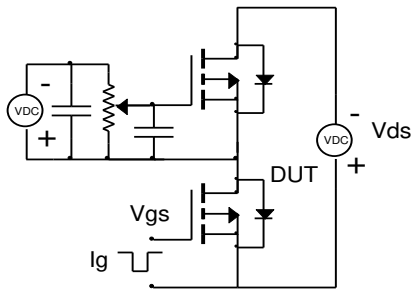
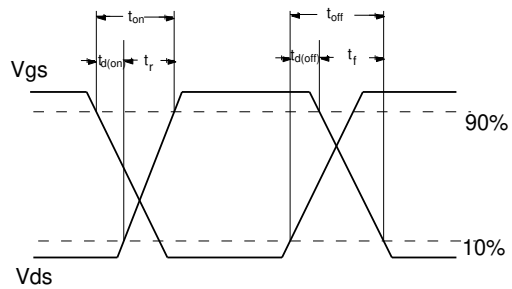
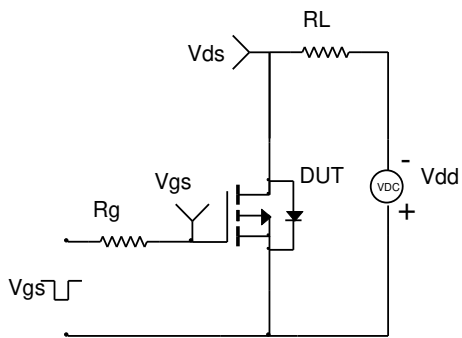


Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)

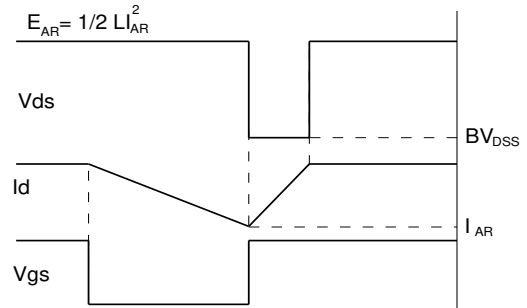
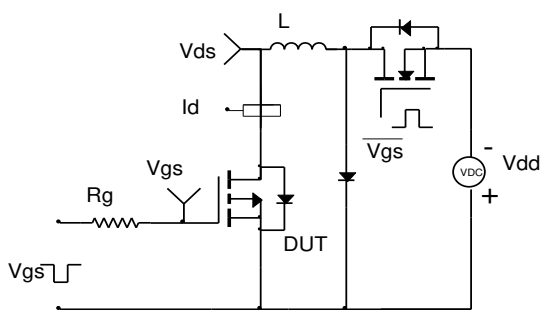
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

